

February 2008

MM74HC164 8-Bit Serial-in/Parallel-out Shift Register

Features

- Typical operating frequency: 50MHz
- Typical propagation delay: 19ns (clock to Q)
- Wide operating supply voltage range: 2V to 6V
- Low input current: 1µA maximum
- Low quiescent supply current: 80µA maximum (74HC Series)
- Fanout of 10 LS-TTL loads

General Description

The MM74HC164 utilizes advanced silicon-gate CMOS technology. It has the high noise immunity and low consumption of standard CMOS integrated circuits. It also offers speeds comparable to low power Schottky devices.

This 8-bit shift register has gated serial inputs and CLEAR. Each register bit is a D-type master/slave flip-flop. Inputs A & B permit complete control over the incoming data. A LOW at either or both inputs inhibits entry of new data and resets the first flip-flop to the low level at the next clock pulse. A high level on one input enables the other input which will then determine the state of the first flip-flop. Data at the serial inputs may be changed while the clock is HIGH or LOW, but only information meeting the setup and hold time requirements will be entered. Data is serially shifted in and out of the 8-bit register during the positive going transition of the clock pulse. Clear is independent of the clock and accomplished by a low level at the CLEAR input.

The 74HC logic family is functionally as well as pin-out compatible with the standard 74LS logic family. All inputs are protected from damage due to static discharge by internal diode clamps to $V_{\rm CC}$ and ground.

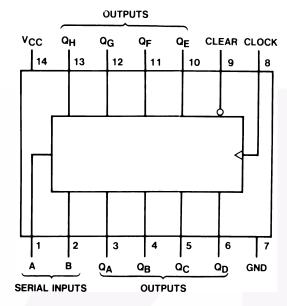
Ordering Information

| _ | | |
|--------------|-------------------|--|
| Order Number | Package Number | Package Description |
| MM74HC164M | M14A | 14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow |
| MM74HC164MTC | MTC14 | 14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide |
| MM74HC164N | N14A | 14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide |

Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering number.

All packages are lead free per JEDEC: J-STD-020B standard.

Connection Diagram



Top View

Truth Table

| | Inputs | | Outputs | | |
|-------|--------|---|---------|-----------------|---------------------------------|
| Clear | Clock | Α | В | Q_A | Q _B Q _H |
| L | Х | Х | Х | L | L L |
| Н | L | Х | Х | Q _{AO} | Q _{BO} Q _{HO} |
| Н | 1 | Н | Н | Н | Q _{An} Q _{Gn} |
| Н | 1 | L | Х | L | Q _A Q _{Gn} |
| Н | 1 | Х | L | L | Q _{An} Q _{Gn} |

H = HIGH Level (steady state)

L = LOW Level (steady state)

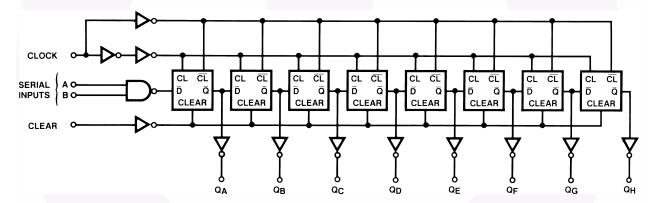
X = Irrelevant (any input, including transitions)

↑ = Transition from LOW-to-HIGH level.

 Q_{AO} , Q_{BO} , Q_{HO} = the level of Q_A , Q_B , or Q_H , respectively, before the indicated steady state input conditions were established.

 ${\sf Q}_{\sf An},\,{\sf Q}_{\sf Gn}=$ The level of ${\sf Q}_{\sf A}$ or ${\sf Q}_{\sf G}$ before the most recent \uparrow transition of the clock; indicated a one-bit shift.

Logic Diagram



Absolute Maximum Ratings⁽¹⁾

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

| Symbol | Parameter | Rating |
|-----------------------------------|--|-------------------------------|
| V _{CC} | Supply Voltage | -0.5 to +7.0V |
| V _{IN} | DC Input Voltage | –1.5 to V _{CC} +1.5V |
| V _{OUT} | DC Output Voltage | –0.5 to V _{CC} +0.5V |
| I _{IK} , I _{OK} | Clamp Diode Current | ±20mA |
| I _{OUT} | DC Output Current, per pin | ±25mA |
| I _{CC} | DC V _{CC} or GND Current, per pin | ±50mA |
| T _{STG} | Storage Temperature Range | −65°C to +150°C |
| P _D | Power Dissipation Note 2 | 600mW |
| | S.O. Package only | 500mW |
| T _L | Lead Temperature (Soldering 10 seconds) | 260°C |

Notes:

- 1. Unless otherwise specified all voltages are referenced to ground.
- 2. Power Dissipation temperature derating plastic "N" package: -12mW/°C from 65°C to 85°C.

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

| Symbol | Parameter | Min. | Max. | Units |
|------------------------------------|--|------|-----------------|-------|
| V _{CC} | Supply Voltage | 2 | 6 | V |
| V _{IN} , V _{OUT} | DC Input or Output Voltage | 0 | V _{CC} | V |
| T _A | Operating Temperature Range | -40 | +85 | °C |
| t _r , t _f | Input Rise or Fall Times $V_{CC} = 2.0V$ | | 1000 | ns |
| | V _{CC} = 4.5V | | 500 | ns |
| | $V_{CC} = 6.0V$ | | 400 | ns |

DC Electrical Characteristics⁽³⁾

| | | | | T _A = | 25°C | T _A =-40°C to 85°C | T _A = -55°C to 125°C | |
|-----------------|-------------------------------------|---------------------|--|-------------------------|------|----------------------------------|------------------------------------|-------|
| Symbol | Parameter | V _{CC} (V) | Conditions | Тур. | | Guaranteed | Limits | Units |
| V _{IH} | Minimum HIGH Level | 2.0 | | | 1.5 | 1.5 | 1.5 | V |
| | Input Voltage | 4.5 | | | 3.15 | 3.15 | 3.15 | |
| | | 6.0 | | | 4.2 | 4.2 | 4.2 | |
| V _{IL} | Maximum LOW Level | 2.0 | | | 0.5 | 0.5 | 0.5 | V |
| | Input Voltage | 4.5 | | | 1.35 | 1.35 | 1.35 | |
| | | 6.0 | | | 1.8 | 1.8 | 1.8 | |
| V _{OH} | Minimum HIGH Level | 2.0 | $V_{IN} = V_{IH}$ or V_{IL} , | 2.0 | 1.9 | 1.9 | 1.9 | V |
| | Output Voltage | 4.5 | I _{OUT} ≤ 20μA | 4.5 | 4.4 | 4.4 | 4.4 | |
| | | 6.0 | | 6.0 | 5.9 | 5.9 | 5.9 | |
| | | 4.5 | $V_{IN} = V_{IH} \text{ or } V_{IL},$ $ I_{OUT} \le 4.0 \text{mA}$ | 4.2 | 3.98 | 3.84 | 3.7 | |
| | | 6.0 | $V_{IN} = V_{IH} \text{ or } V_{IL},$ $ I_{OUT} \le 5.2 \text{mA}$ | 5.7 | 5.48 | 5.34 | 5.2 | |
| V _{OL} | | | $V_{IN} = V_{IH}$ or V_{IL} , | 0 | 0.1 | 0.1 | 0.1 | V |
| | Output Voltage | 4.5 | I _{OUT} ≤ 20µA | 0 | 0.1 | 0.1 | 0.1 | |
| | | 6.0 | | 0 | 0.1 | 0.1 | 0.1 | |
| | | 4.5 | $V_{IN} = V_{IH} \text{ or } V_{IL},$ $ I_{OUT} \le 4.0 \text{mA}$ | 0.2 | 0.26 | 0.33 | 0.4 | |
| | | 6.0 | $V_{IN} = V_{IH} \text{ or } V_{IL},$ $ I_{OUT} \le 5.2 \text{mA}$ | 0.2 | 0.26 | 0.33 | 0.4 | |
| I _{IN} | Maximum Input Current | 6.0 | $V_{IN} = V_{CC}$ or GND | | ±0.1 | ±1.0 | ±1.0 | μA |
| I _{CC} | Maximum Quiescent Supply Current | 6.0 | $V_{IN} = V_{CC}$ or GND, $I_{OUT} = 0\mu A$ | | 8.0 | 80 | 160 | μA |

Note:

3. For a power supply of 5V $\pm 10\%$ the worst case output voltages (V_{OH}, and V_{OL}) occur for HC at 4.5V. Thus the 4.5V values should be used when designing with this supply. Worst case V_{IH} and V_{IL} occur at V_{CC} = 5.5V and 4.5V respectively. (The V_{IH} value at 5.5V is 3.85V.) The worst case leakage current (I_{IN}, I_{CC}, and I_{OZ}) occur for CMOS at the higher voltage and so the 6.0V values should be used.

AC Electrical Characteristics

 $V_{CC} = 5V$, $T_A = 25$ °C, $C_L = 15$ pF, $t_r = t_f = 6$ ns

| Symbol | Parameter | Conditions | Тур. | Guaranteed Limit | Units |
|-------------------------------------|--|------------|------|---------------------|-------|
| f _{MAX} | Maximum Operating Frequency | | | 30 | MHz |
| t _{PHL} , t _{PLH} | Maximum Propagation Delay, Clock to Output | | 19 | 30 | ns |
| t _{PHL} | Maximum Propagation Delay, Clear to Output | | 23 | 35 | ns |
| t _{REM} | Minimum Removal Time, Clear to Clock | | -2 | 0 | ns |
| t _S | Minimum Setup Time, Data to Clock | | 12 | 20 | ns |
| t _H | Minimum Hold Time, Clock to Data | | 1 | 5 | ns |
| t _W | Minimum Pulse Width, Clear or Clock | | 10 | 16 | ns |

AC Electrical Characteristics

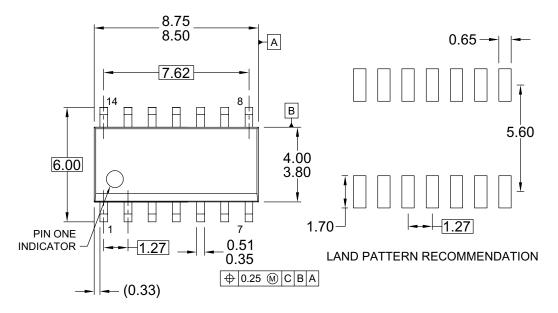
 $C_L = 50 pF$, $t_r = t_f = 6 ns$ (unless otherwise specified)

| | | | | T _A = | 25°C | T _A =-40°C to 85°C | T _A = -55°C to 125°C | |
|-------------------------------------|---|---------------------|---------------|-------------------------|------|----------------------------------|------------------------------------|-------|
| Symbol | Parameter | V _{CC} (V) | Conditions | Тур. | | Guaranteed | Limits | Units |
| f _{MAX} | Maximum Operating | 2.0 | | | 5 | 4 | 3 | MHz |
| | Frequency | 4.5 | | | 27 | 21 | 18 | |
| | | 6.0 | | | 31 | 24 | 20 | |
| t _{PHL} , t _{PLH} | Maximum Propagation | 2.0 | | 115 | 175 | 218 | 254 | ns |
| | Delay, Clock to Output | 4.5 | | 13 | 35 | 44 | 51 | |
| | | 6.0 | | 20 | 30 | 38 | 44 | |
| t _{PHL} | Maximum Propagation | 2.0 | | 140 | 205 | 256 | 297 | ns |
| | Delay, Clear to Output | 4.5 | | 28 | 41 | 51 | 59 | |
| | | 6.0 | | 24 | 35 | 44 | 51 | |
| t _{REM} | Minimum Removal | 2.0 | | -7 | 0 | 0 | 0 | ns |
| | Time, Clear to Clock | 4.5 | | -3 | 0 | 0 | 0 | |
| | | 6.0 | | -2 | 0 | 0 | 0 | |
| t _S | t _S Minimum Setup Time, | 2.0 | | 25 | 100 | 125 | 150 | ns |
| | Data to Clock | 4.5 | | 14 | 20 | 25 | 30 | |
| | | 6.0 | | 12 | 17 | 21 | 25 | |
| t _H | Minimum Hold Time, | 2.0 | | -2 | 5 | 5 | 5 | ns |
| | Clock to Data | 4.5 | | 0 | 5 | 5 | 5 | |
| | | 6.0 | | 1 | 5 | 5 | 5 | |
| t _W | Minimum Pulse Width | 2.0 | | 22 | 80 | 100 | 120 | ns |
| | Clear or Clock | 4.5 | | 11 | 16 | 20 | 24 | |
| | | 6.0 | | 10 | 14 | 18 | 20 | |
| t _{THL} , t _{TLH} | Maximum Output | 2.0 | | | 75 | 95 | 110 | ns |
| | Rise and Fall Time | 4.5 | | | 15 | 19 | 22 | |
| | | 6.0 | | | 13 | 16 | 19 | |
| t _r , t _f | Maximum Input | 2.0 | | | 1000 | 1000 | 1000 | ns |
| | Rise and Fall Time | 4.5 | | | 500 | 500 | 500 | |
| | | 6.0 | | | 400 | 400 | 400 | |
| C _{PD} | Power Dissipation Capacitance ⁽⁴⁾ | 5.0 | (per package) | 150 | | | | pF |
| C _{IN} | Maximum Input Capacitance | | | 5 | 10 | 10 | 10 | pF |

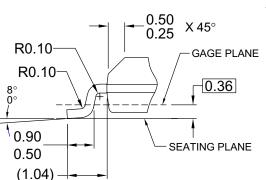
Note:

4. C_{PD} determines the no load dynamic power consumption, $P_D = C_{PD} \ V_{CC}^2 \ f + I_{CC} \ V_{CC}$, and the no load dynamic current consumption, $I_S = C_{PD} \ V_{CC} \ f + I_{CC}$.

Physical Dimensions







DETAIL A

- A) THIS PACKAGE CONFORMS TO JEDEC MS-012, VARIATION AB, ISSUE C,
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS.
- D) LANDPATTERN STANDARD: SOIC127P600X145-14M
- E) DRAWING CONFORMS TO ASME Y14.5M-1994
- F) DRAWING FILE NAME: M14AREV13

Figure 1. 14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow

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Physical Dimensions (Continued) 5.0±0.1 -A-0.65 0.43 TYP 6.4 4.4±0.1 -B-1.65 3.2 □ 0.2 C B A PIN #1 IDENT. 6.10 0.45LAND PATTERN RECOMMENDATION SEE DETAIL A ALL LEAD TIPS 0.90+0.15 1.2 MAX □ 0.1 C 0.09-0.20 -C-0.10±0.05 0.65 0.19 - 0.30⊕ |0.13\(\omega \ \omega \omega \ \omega \ \omega \ \omega \ \omega \omega \ \omeg 12.00°TOP & BOTTOM R0.09 min GAGE PLANE 0.25 0°-8° NOTES: 0.6±0.1 A. CONFORMS TO JEDEC REGISTRATION MO-153, SEATING PLANE R0.09min VARIATION AB, REF NOTE 6 1 00 **B. DIMENSIONS ARE IN MILLIMETERS DETAIL A**

- C. DIMENSIONS ARE IN MILLIMETERS

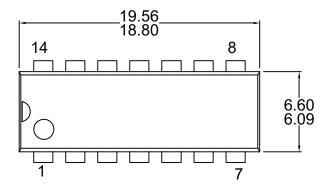
 C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
- D. DIMENSIONING AND TOLERANCES PER ANSI Y14.5M, 1982
- E. LANDPATTERN STANDARD: SOP65P640X110-14M
- F. DRAWING FILE NAME: MTC14REV6

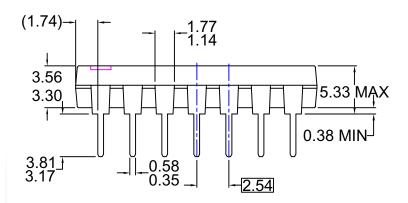
Figure 2. 14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

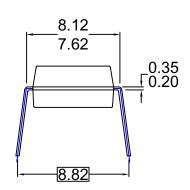
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Physical Dimensions (Continued)







NOTES: UNLESS OTHERWISE SPECIFIED THIS PACKAGE CONFORMS TO

- A) JEDEC MS-001 VARIATION BA
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
 DIMENSIONS ARE EXCLUSIVE OF BURRS.
- C) MOLD FLASH, AND TIE BAR EXTRUSIONS.
- D) DIMENSIONS AND TOLERANCES PER ASME Y14.5-1994
- E) DRAWING FILE NAME: MKT-N14AREV7

Figure 3. 14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

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